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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	256KB (128K x 16)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atxmega256d3-anr

6. AVR CPU

6.1 Features

- 8/16-bit, high-performance Atmel AVR RISC CPU
 - 137 instructions
 - Hardware multiplier
- 32x8-bit registers directly connected to the ALU
- Stack in RAM
- Stack pointer accessible in I/O memory space
- Direct addressing of up to 16MB of program memory and 16MB of data memory
- True 16/24-bit access to 16/24-bit I/O registers
- Efficient support for 8-, 16-, and 32-bit arithmetic
- Configuration change protection of system-critical features

6.2 Overview

All Atmel AVR XMEGA devices use the 8/16-bit AVR CPU. The main function of the CPU is to execute the code and perform all calculations. The CPU is able to access memories, perform calculations, control peripherals, and execute the program in the flash memory. Interrupt handling is described in a separate section, refer to "Interrupts and Programmable Multilevel Interrupt Controller" on page 28.

6.3 Architectural Overview

In order to maximize performance and parallelism, the AVR CPU uses a Harvard architecture with separate memories and buses for program and data. Instructions in the program memory are executed with single-level pipelining. While one instruction is being executed, the next instruction is pre-fetched from the program memory. This enables instructions to be executed on every clock cycle. For details of all AVR instructions, refer to www.atmel.com/avr.



Register File

R31 (ZH) R30 (ZL)
R29 (YH) R28 (XL)
R27 (XH) R26 (XL)
R28 R22
R23 R22
R21 R20
R19 R18
R17 R16
R15 R14
R13 R12
R11 R10
R9 R8
R7 R6
R5 R4
R3 R2
R1 R0

Instruction
Register

Stack
Pointer

ALU

Data Memory

Data Memory

Figure 6-1. Block Diagram of the AVR CPU Architecture

The arithmetic logic unit (ALU) supports arithmetic and logic operations between registers or between a constant and a register. Single-register operations can also be executed in the ALU. After an arithmetic operation, the status register is updated to reflect information about the result of the operation.

The ALU is directly connected to the fast-access register file. The 32 * 8-bit general purpose working registers all have single clock cycle access time allowing single-cycle arithmetic logic unit (ALU) operation between registers or between a register and an immediate. Six of the 32 registers can be used as three 16-bit address pointers for program and data space addressing, enabling efficient address calculations.

The memory spaces are linear. The data memory space and the program memory space are two different memory spaces.

The data memory space is divided into I/O registers, SRAM, and external RAM. In addition, the EEPROM can be memory mapped in the data memory.

All I/O status and control registers reside in the lowest 4KB addresses of the data memory. This is referred to as the I/O memory space. The lowest 64 addresses can be accessed directly, or as the data space locations from 0x00 to 0x3F. The rest is the extended I/O memory space, ranging from 0x0040 to 0x0FFF. I/O registers here must be accessed as data space locations using load (LD/LDS/LDD) and store (ST/STS/STD) instructions.

The SRAM holds data. Code execution from SRAM is not supported. It can easily be accessed through the five different addressing modes supported in the AVR architecture. The first SRAM address is 0x2000.

Data addresses 0x1000 to 0x1FFF are reserved for memory mapping of EEPROM.

The program memory is divided in two sections, the application program section and the boot program section. Both sections have dedicated lock bits for write and read/write protection. The SPM instruction that is used for self-programming of the application flash memory must reside in the boot program section. The application section contains an application table section with separate lock bits for write and read/write protection. The application table section can be used for safe storing of nonvolatile data in the program memory.



22. USART

22.1 Features

- Three identical USART peripherals
- Full-duplex operation
- Asynchronous or synchronous operation
 - Synchronous clock rates up to 1/2 of the device clock frequency
 - Asynchronous clock rates up to 1/8 of the device clock frequency
- Supports serial frames with 5, 6, 7, 8, or 9 data bits and 1 or 2 stop bits
- Fractional baud rate generator
 - Can generate desired baud rate from any system clock frequency
 - No need for external oscillator with certain frequencies
- Built-in error detection and correction schemes
 - Odd or even parity generation and parity check
 - Data overrun and framing error detection
 - · Noise filtering includes false start bit detection and digital low-pass filter
- Separate interrupts for
 - Transmit complete
 - Transmit data register empty
 - Receive complete
- Multiprocessor communication mode
 - Addressing scheme to address a specific devices on a multidevice bus
 - Enable unaddressed devices to automatically ignore all frames
- Master SPI mode
 - Double buffered operation
 - Operation up to 1/2 of the peripheral clock frequency
- IRCOM module for IrDA compliant pulse modulation/demodulation

22.2 Overview

The universal synchronous and asynchronous serial receiver and transmitter (USART) is a fast and flexible serial communication module. The USART supports full-duplex communication and asynchronous and synchronous operation. The USART can be configured to operate in SPI master mode and used for SPI communication.

Communication is frame based, and the frame format can be customized to support a wide range of standards. The USART is buffered in both directions, enabling continued data transmission without any delay between frames. Separate interrupts for receive and transmit complete enable fully interrupt driven communication. Frame error and buffer overflow are detected in hardware and indicated with separate status flags. Even or odd parity generation and parity check can also be enabled.

The clock generator includes a fractional baud rate generator that is able to generate a wide range of USART baud rates from any system clock frequencies. This removes the need to use an external crystal oscillator with a specific frequency to achieve a required baud rate. It also supports external clock input in synchronous slave operation.

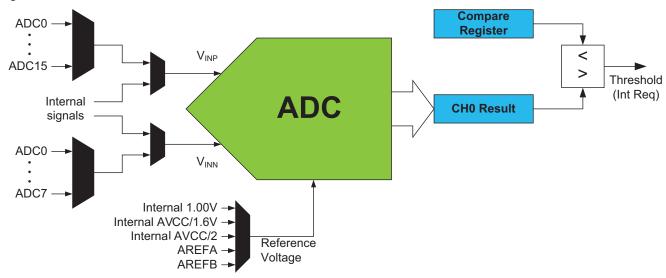
When the USART is set in master SPI mode, all USART-specific logic is disabled, leaving the transmit and receive buffers, shift registers, and baud rate generator enabled. Pin control and interrupt generation are identical in both modes. The registers are used in both modes, but their functionality differs for some control settings.

An IRCOM module can be enabled for one USART to support IrDA 1.4 physical compliant pulse modulation and demodulation for baud rates up to 115.2kbps.

PORTC, PORTD, and PORTE each has one USART. Notation of these peripherals are USARTC0, USARTD0, and USARTE0, respectively.



Figure 25-1. ADC Overview



The ADC may be configured for 8- or 12-bit result, reducing the minimum conversion time (propagation delay) from 3.35µs for 12-bit to 2.3µs for 8-bit result.

ADC conversion results are provided left- or right adjusted with optional '1' or '0' padding. This eases calculation when the result is represented as a signed integer (signed 16-bit number).

PORTA has one ADC. Notation of this peripheral is ADCA.



32.4 Atmel ATxmega192D3

32.4.1 Absolute Maximum Ratings

Stresses beyond those listed in Table 32-88 may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 32-88. Absolute Maximum Ratings

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{CC}	Power supply voltage		-0.3		4	V
I _{vcc}	Current into a V _{CC} pin				200	mA
I _{GND}	Current out of a Gnd pin				200	IIIA
V_{PIN}	Pin voltage with respect to Gnd and V_{CC}		-0.5		V _{CC} + 0.5	V
I _{PIN}	I/O pin sink/source current		-25		25	mA
T _A	Storage temperature		-65		150	°C
T _j	Junction temperature				150	C

32.4.2 General Operating Ratings

The device must operate within the ratings listed in Table 32-89 in order for all other electrical characteristics and typical characteristics of the device to be valid.

Table 32-89. General Operating Conditions

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{CC}	Power supply voltage		1.60		3.6	V
AV _{CC}	Analog supply voltage		1.60		3.6	V
T _A	Temperature range		-40		85	°C
T _j	Junction temperature		-40		105	

Table 32-90. Operating Voltage and Frequency

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
Clk _{CPU}	CPU clock frequency	V _{CC} = 1.6V	0		12	MHz
		V _{CC} = 1.8V	0		12	
		V _{CC} = 2.7V	0		32	
		V _{CC} = 3.6V	0		32	

The maximum CPU clock frequency depends on V_{CC} . As shown in Figure 32-22 on page 121 the frequency vs. V_{CC} curve is linear between 1.8V < V_{CC} < 2.7V.



32.5.13.5 Internal Phase Locked Loop (PLL) Characteristics

Table 32-139. Internal PLL Characteristics

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
f _{IN}	Input frequency	Output frequency must be within f _{OUT}	0.4		64	
f	Output frequency (1)	V _{CC} = 1.6 - 1.8V	20		48	MHz
f _{OUT}	Output frequency V	V _{CC} = 2.7 - 3.6V	20		128	
	Start-up time			25		III C
	Re-lock time			25		μs

Note: 1. The maximum output frequency vs. supply voltage is linear between 1.8V and 2.7V, and can never be higher than four times the maximum CPU frequency.

32.5.13.6 External Clock Characteristics

Figure 32-31.External Clock Drive Waveform

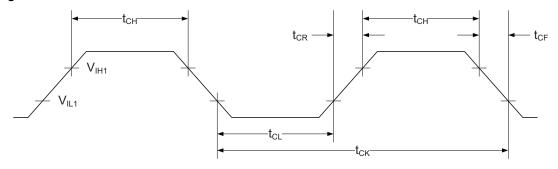


Table 32-140.External Clock used as System Clock without Prescaling

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
1 /4	Clock Frequency (1)	V _{CC} = 1.6 - 1.8V	0		12	MHz
1/t _{CK}	Clock Frequency V	V _{CC} = 2.7 - 3.6V	0		32	IVIITZ
4	Clock Period	V _{CC} = 1.6 - 1.8V	83.3			
t _{CK}	CIOCK P GIIOU	V _{CC} = 2.7 - 3.6V	31.5			
4	Clock High Time	V _{CC} = 1.6 - 1.8V	30.0			
t _{CH}		V _{CC} = 2.7 - 3.6V	12.5			
4	Clock Low Time	V _{CC} = 1.6 - 1.8V	30.0			ns
t _{CL}		V _{CC} = 2.7 - 3.6V	12.5			113
4	Pico Timo (for maximum fraguancy)	V _{CC} = 1.6 - 1.8V			10	
t _{CR}	Rise Time (for maximum frequency)	V _{CC} = 2.7 - 3.6V			3	
4	Fall Time (for more income for more a)	V _{CC} = 1.6 - 1.8V			10	
t _{CF}	Fall Time (for maximum frequency)	V _{CC} = 2.7 - 3.6V			3	
Δt _{CK}	Change in period from one clock cycle to the next				10	%

Note: 1. The maximum frequency vs. supply voltage is linear between 1.6V and 2.7V, and the same applies for all other parameters with supply voltage conditions.



Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{in}	Input range		0		V_{REF}	
	Conversion range	Differential mode, Vinp - Vinn	-V _{REF}		V _{REF}	V
	Conversion range	Single ended unsigned mode, Vinp	-ΔV		V _{REF} - ΔV	
ΔV	Fixed offset voltage			200		lsb

Table 32-154. Clock and Timing

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
CIL	ADO als all fra more	Maximum is 1/4 of peripheral clock frequency	100		1800	kHz
Clk _{ADC}	ADC clock frequency	Measuring internal signals	100		125	NI IZ
f _{ClkADC}	Sample rate		16		300	
		Current limitation (CURRLIMIT) off	16		300	
f	Sample rate	CURRLIMIT = LOW	16		250	ksps
f _{ADC}		CURRLIMIT = MEDIUM	16		150	
		CURRLIMIT = HIGH	16		50	
	Sampling time	Configurable in steps of 1/2 Clk_{ADC} cycles up to 32 Clk_{ADC} cycles	0.28		320	μs
	Conversion time (latency)	(RES+1)/2 + GAIN RES (Resolution) = 8 or 12, GAIN = 0 to 3	5.5		10	Clk _{ADC}
	Start-up time	ADC clock cycles		12	24	
	ADC settling time	After changing reference or input mode		7	7	



33.1.6 BOD Characteristics

Figure 33-47. BOD Thresholds vs. Temperature BOD level = 1.6V

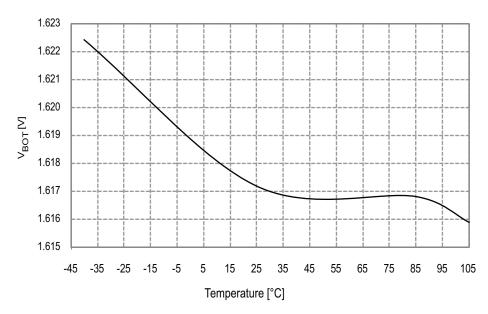
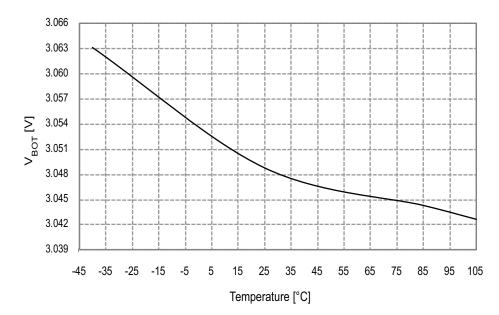


Figure 33-48. BOD Thresholds vs. Temperature BOD level = 3.0V





33.1.8.2 32.768kHz Internal Oscillator

Figure 33-55. 32.768kHz Internal Oscillator Frequency vs. Temperature

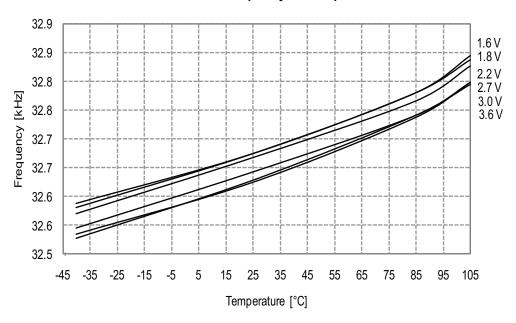


Figure 33-56. 32.768kHz Internal Oscillator Frequency vs. Calibration Value V_{CC} = 3.0V, T = 25°C

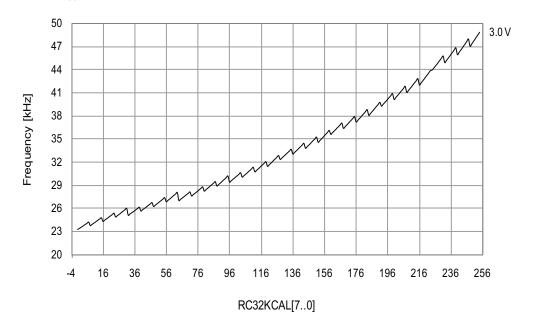




Figure 33-153. Idle Mode Supply Current vs. V_{CC} $f_{SYS} = 1MHz$ external clock

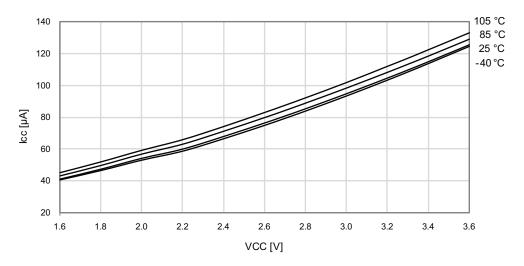


Figure 33-154. Idle Mode Supply Current vs. V_{CC} $f_{SYS} = 2MHz$ internal oscillator

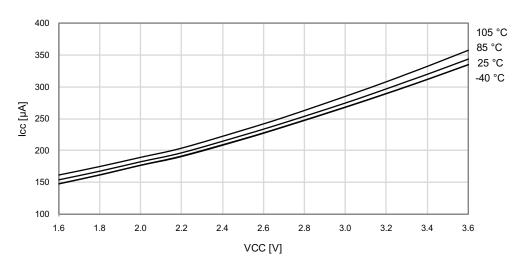
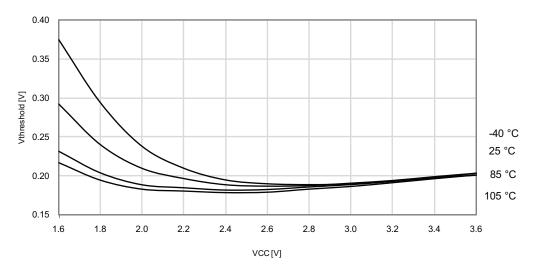


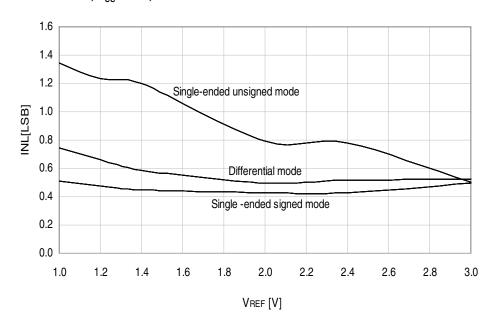


Figure 33-171. I/O Pin Input Hysteresis vs. $V_{\rm CC}$



33.3.3 ADC Characteristics

Figure 33-172. INL Error vs. External V_{REF} $T = 25 \, \text{C}, V_{CC} = 3.6 V, \text{ external reference}$





33.3.4 Analog Comparator Characteristics

Figure 33-183. Analog Comparator Hysteresis vs. V_{CC} Small hysteresis

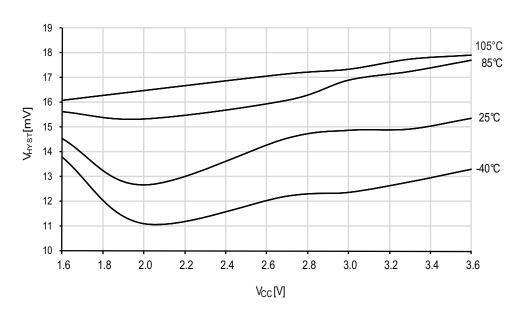
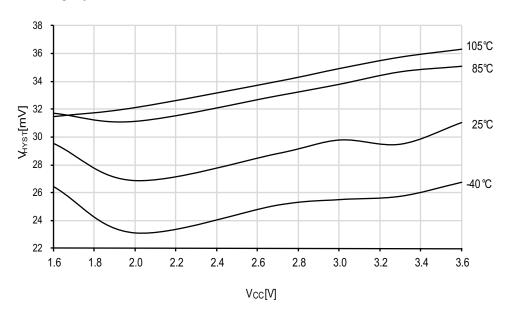


Figure 33-184. Analog Comparator Hysteresis vs. V_{CC}

Large hysteresis





33.3.8.4 32MHz Internal Oscillator

Figure 33-201. 32MHz Internal Oscillator Frequency vs. Temperature DFLL disabled

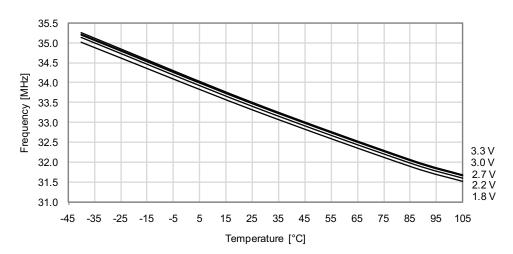


Figure 33-202. 32MHz Internal Oscillator Frequency vs. Temperature DFLL enabled, from the 32.768kHz internal oscillator

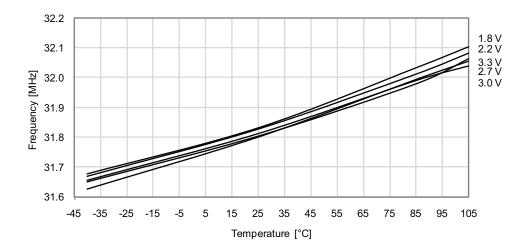




Figure 33-223.Idle Mode Supply Current vs. V_{CC} $f_{SYS} = 1MHz$ external clock

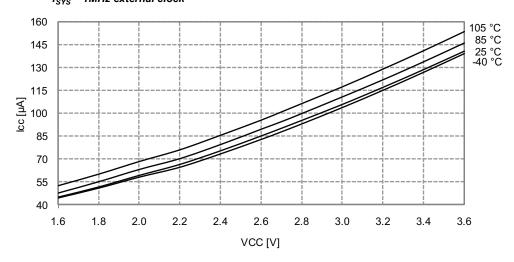
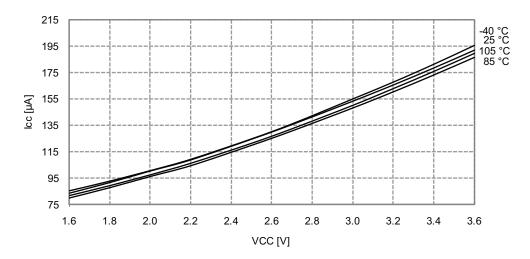


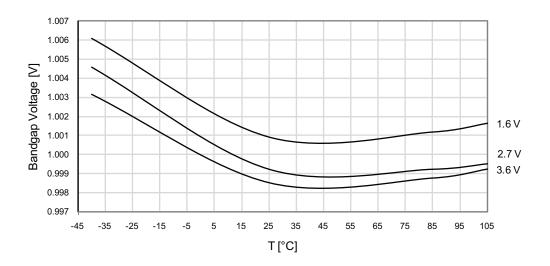
Figure 33-224.Idle Mode Supply Current vs. V_{CC} $f_{SYS} = 2MHz internal oscillator$





33.4.5 Internal 1.0V Reference Characteristics

Figure 33-257.ADC Internal 1.0V Reference vs. Temperature



33.4.6 BOD Characteristics

Figure 33-258.BOD Thresholds vs. Temperature BOD level = 1.6V

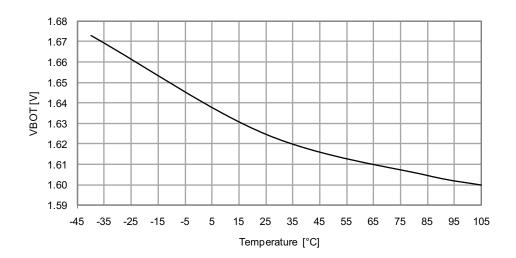




Figure 33-273. 32MHz Internal Oscillator CALA Calibration Step Size T = -40 °C, $V_{CC} = 3.0V$

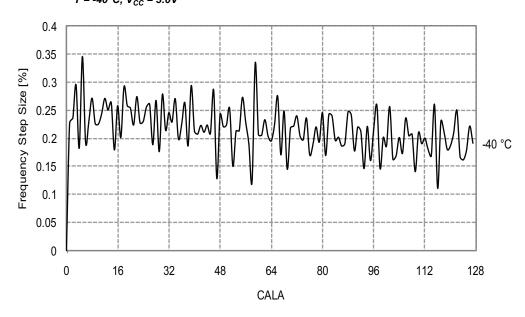
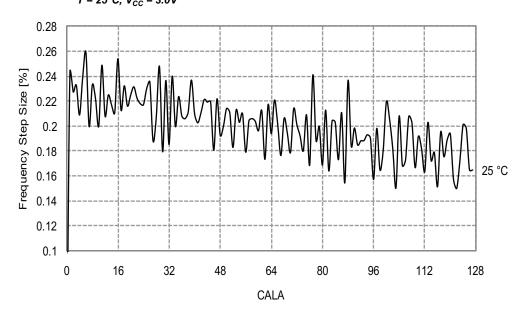


Figure 33-274. 32MHz Internal Oscillator CALA Calibration Step Size $T=25^{\circ}C$, $V_{CC}=3.0V$





```
2.4 V
 1×
      gain:
 2×
      gain:
              1.2 V
4×
      gain:
              0.6 V
8×
      gain:
              300 mV
16×
      gain:
              150 mV
32×
      gain:
              75
                   mV
64×
      gain:
               38 mV
```

Problem fix/workaround

Keep the amplified voltage output from the ADC gain stage below 2.4V in order to get a correct result, or keep ADC voltage reference below 2.4V.

6. ADC Event on compare match non-functional

ADC signalling event will be given at every conversion complete even if Interrupt mode (INTMODE) is set to BELOW or ABOVE.

Problem fix/workaround

Enable and use interrupt on compare match when using the compare function.

7. ADC propagation delay is not correct when 8x - 64x gain is used

The propagation delay will increase by only one ADC clock cycle for all gain settings.

Problem fix/workaround

None.

8. Bandgap measurement with the ADC is non-functional when V_{CC} is below 2.7V

The ADC can not be used to do bandgap measurements when V_{CC} is below 2.7V.

Problem fix/workaround

None.

9. Accuracy lost on first three samples after switching input to ADC gain stage

Due to memory effect in the ADC gain stage, the first three samples after changing input channel must be disregarded to achieve 12-bit accuracy.

Problem fix/workaround

Run three ADC conversions and discard these results after changing input channels to ADC gain stage.

10. Configuration of PGM and CWCM not as described in XMEGA D Manual

Enabling Common Waveform Channel Mode will enable Pattern generation mode (PGM), but not Common Waveform Channel Mode.

Enabling Pattern Generation Mode (PGM) and not Common Waveform Channel Mode (CWCM) will enable both Pattern Generation Mode and Common Waveform Channel Mode.



Problem fix/workaround

Table 34-3. Configure PWM and CWCM According to this Table:

PGM	CWCM	Description
0	0	PGM and CWCM disabled
0	1	PGM enabled
1	0	PGM and CWCM enabled
1	1	PGM enabled

11. PWM is not restarted properly after a fault in cycle-by-cycle mode

When the AWeX fault restore mode is set to cycle-by-cycle, the waveform output will not return to normal operation at first update after fault condition is no longer present.

Problem fix/workaround

Do a write to any AWeX I/O register to re-enable the output.

12. BOD will be enabled after any reset

If any reset source goes active, the BOD will be enabled and keep the device in reset if the V_{CC} voltage is below the programmed BOD level. During Power-On Reset, reset will not be released until V_{CC} is above the programmed BOD level even if the BOD is disabled.

Problem fix/workaround

Do not set the BOD level higher than V_{CC} even if the BOD is not used.

13. EEPROM page buffer always written when NVM DATA0 is written

If the EEPROM is memory mapped, writing to NVM DATA0 will corrupt data in the EEPROM page buffer.

Problem fix/workaround

Before writing to NVM DATA0, for example when doing software CRC or flash page buffer write, check if EEPROM page buffer active loading flag (EELOAD) is set. Do not write NVM DATA0 when EELOAD is set.

14. Pending full asynchronous pin change interrupts will not wake the device

Any full asynchronous pin-change Interrupt from pin 2, on any port, that is pending when the sleep instruction is executed, will be ignored until the device is woken from another source or the source triggers again. This applies when entering all sleep modes where the System Clock is stopped.

Problem fix/workaround

None.

15. Pin configuration does not affect Analog Comparator output

The Output/Pull and inverted pin configuration does not affect the Analog Comparator output.

Problem fix/workaround

None for Output/Pull configuration.

For inverted I/O, configure the Analog Comparator to give an inverted result (that is, connect positive input to the negative AC input and vice versa), or use and external inverter to change polarity of Analog Comparator output.



34.4.9 Rev. A

Not sampled.



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